

11th International Congress on Thermal Stresses 2016

June 5–9, 2016, Salerno, Italy
First Announcement and Call for Papers



TIME AND PLACE

The Congress will be held from June 5 to 9, 2016, near the campus of the University of Salerno, Italy. The accommodation will be organized in nearby hotels within walking distance.

AIM

The objectives of the Congress are to provide a forum for scientists and engineers from academia, research laboratories, and industry from all over the world who are involved in the field of thermal stresses to exchange ideas and to extend further cooperation among participants. The Congress should forge cooperative links between researchers and engineers by bringing them to one place where they present their achievements and conduct discussions.

TOPICS

This is a conference on thermal stresses and related topics, with particular focus on the following, but not limited to them:

- ◆ Thermal Stresses and Deformations
- ◆ Thermoelasticity and Viscoelasticity
- ◆ Thermal Stresses in
 - ◆ Contact Mechanics,
 - ◆ Dynamic Problems,
 - ◆ Fracture and Fatigue of Heterogeneous Materials and Manufacturing
- ◆ Thermo-Hygro-Mechanics
- ◆ Thermo-Biomechanics

- ◆ Thermal Shock
- ◆ Continuum Thermomechanics
- ◆ Heat Conduction, Convection and Radiation Problems
- ◆ Experimental Methods in Thermomechanics
- ◆ Computational Methods in Thermomechanics
- ◆ Control of Thermal Structures
- ◆ Instability and Localization under Thermomechanic Loading
- ◆ Inverse and Optimization Methods in Thermomechanics
- ◆ Thermal Stresses in Smart Materials
- ◆ Thermal-Induced Fracture of Smart Materials

ABSTRACTS AND PAPERS

An abstract of presentation of about 500 words or of half-page length with title, name, address, phone/fax number and e-mail address should be submitted to the Secretariat of TS 2016. Decision on the presentation will be sent to the authors. And detailed instructions on preparations of 4-page papers and poster presentations will be given on the Congress' website (under construction). The 4-page papers (not more and not less) will be published in the Proceedings. Authors will be encouraged to submit the full papers for publication in the Mechanics journals, in particular, in the Journal of Thermal Stresses.

IMPORTANT DEADLINES

Submission of an abstract: November 30, 2015
Notification of acceptance: January 15, 2016
Submission of the 4-page paper: February 29, 2016

CHAIRS

General Chair

Prof. Michele Ciarletta
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Co-Chairs

Prof. Richard B Hetnarski
Rochester Institute of Technology, USA
Prof. Naotake Noda
Shizuoka University, Japan

SOCIAL PROGRAMS

Rich program is scheduled, including sightseeing.

PREVIOUS CONGRESSES ON THERMAL STRESSES

10th Nanjing, China 2013

Nanjing University of Aeronautics and Astronautics

9th Budapest, Hungary 2011

Budapest University of Technology and Economics and
Hungarian Academy of Sciences

8th Urbana-Champaign, Illinois, USA 2009

University of Illinois

7th Taipei, Taiwan 2007

National Taiwan University of Science and Technology

6th Vienna, Austria 2005

Vienna University of Technology

5th Blacksburg, USA 2003

Virginia Polytechnic Institute and State University

4th Osaka, Japan 2001

Osaka Prefecture University, Osaka Institute of
Technology

3rd Cracow, Poland 1999

Cracow University of Technology

2nd Rochester, USA 1997

Rochester Institute of Technology

1st Hamamatsu, Japan 1995

Shizuoka University

CORRESPONDENCE

Secretariat of TS 2016

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